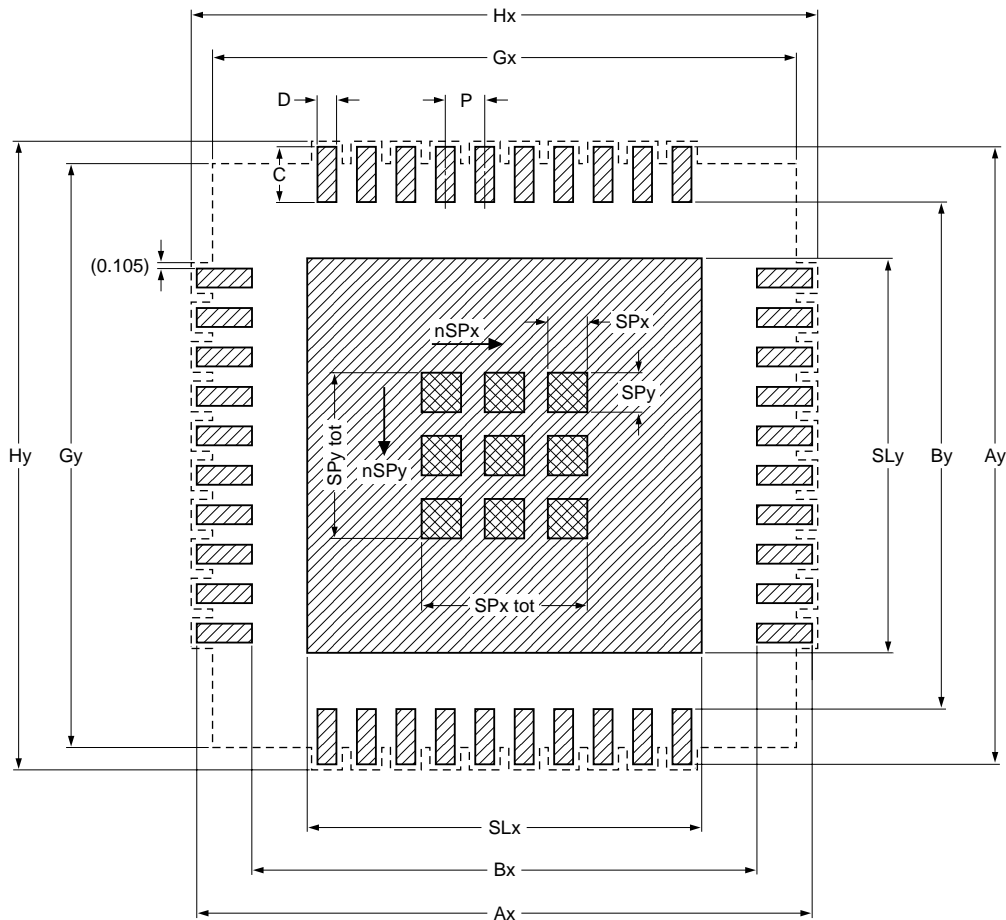





Footprint information for reflow soldering of HVQFN32 package

SOT617-3



Generic footprint pattern

Refer to the package outline drawing for actual layout

-  solder land
-  solder paste deposit
-  solder land plus solder paste
- occupied area

nSPx	nSPy
3	3

DIMENSIONS in mm

P	Ax	Ay	Bx	By	C	D	SLx	SLy	SPx tot	SPy tot	SPx	SPy	Gx	Gy	Hx	Hy
0.500	6.000	6.000	4.200	4.200	0.900	0.290	3.500	3.500	2.100	2.100	0.500	0.500	5.300	5.300	6.250	6.250